



[10191/3399]

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : 10/691,108 Confirmation No. 4772
Applicant : Klaus BREITSCHWERDT
Filed : October 22, 2003
Title : DEVICE AND METHOD FOR ANISOTROPIC PLASMA ETCHING
OF A SUBSTRATE, PARTICULARLY A SILICON ELEMENT
TC/A.U. : 1765
Examiner : Lan Vinh

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450 on:

Date:

Jun 8, 2006

Signature:

Chih

RESPONSE

Sir:

This paper is responsive to the Office Action dated January 5, 2006 in connection with the above-captioned application.

Remarks begin on page 2 of this paper.

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